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AC857BSQ

45V DUAL PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Description

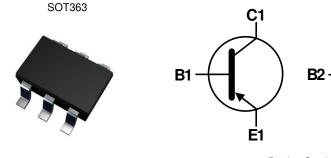
This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirement of Automotive Applications.

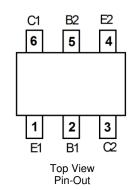
Features

- Ultra-Small Surface Mount Package
- Ideally Suited for Automated Insertion
- For Switching and AF Amplifier Application
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Finish. Solderable per MIL-STD-202, Method 208 (a)
- Weight: 0.006 grams (Approximate)





February 2017

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Top View

Device Symbol

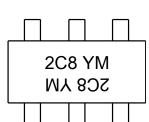
Ordering Information (Notes 4 & 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
AC857BSQ-7	Automotive	2C8	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



SOT363

2C8 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: D = 2016)

M = Month (ex: 9 = September)

Date Code Key

Year	2016	20	017	2018	2	019	2020	:	2021	2022		2023
Code	D		E	F		G	Н			J		K
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-50	V
Collector-Emitter Voltage	V _{CEO}	-45	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	I _C	-100	mA
Peak Collector Current	I _{CM}	-200	mA
Peak Base Current	I _{BM}	-200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P_{D}	200	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	$R_{\theta JA}$	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic (Note 7)	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	-50	_	_	V	$I_C = -100 \mu A, I_B = 0$
Collector-Emitter Breakdown Voltage	BV _{CEO}	-45	_	_	V	$I_C = -10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	-5	_	_	V	$I_E = -100 \mu A, I_C = 0$
DC Current Gain	h _{FE}	220	_	475	_	$V_{CE} = -5.0V, I_{C} = -2.0mA$
Collector-Emitter Saturation Voltage	V	_	_	-100 -400	mV	$I_C = -10 \text{mA}, I_B = -0.5 \text{mA}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}					$I_C = -100 \text{mA}, I_B = -5.0 \text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	_	-700	_	mV	$I_C = -10mA$, $I_B = -0.5mA$
Base-Emitter Voltage	$V_{BE(ON)}$	-580	-665	-750	mV	$V_{CE} = -5.0V, I_{C} = -2.0mA$
Collector-Cutoff Current	lone	_	_	-15	nA	$V_{CB} = -30V$
Collector-Outon Current	I _{CBO}		_	-4.0	μΑ	$V_{CB} = -30V, T_A = +150$ °C
Emitter Cutoff Current	I _{EBO}	_	_	-100	nA	$V_{EB} = -5.0V, I_{C} = 0$
Gain Bandwidth Product	f⊤	100	_	_	MHz	$V_{CE} = -5.0V, I_{C} = -10mA,$ f = 100MHz
Collector-Base Capacitance	Ссво	_	2	3	pF	V _{CB} = -10V, f = 1.0MHz
Emitter-Base Capacitance	C _{EBO}	_	11	_	pF	$V_{EB} = -0.5V, f = 1.0MHz$

Notes:

^{6.} For the device mounted on minimum recommended pad layout FR-4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.7. Short duration pulse test used to minimize self-heating effect.



Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

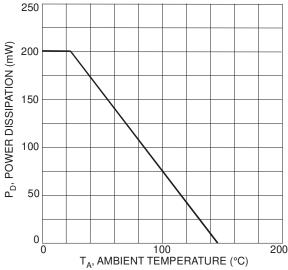


Fig. 1 Power Dissipation vs. Ambient Temperature

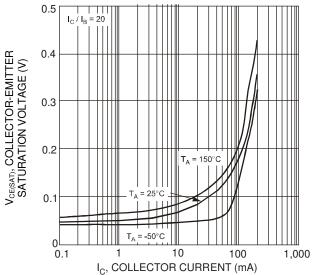


Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

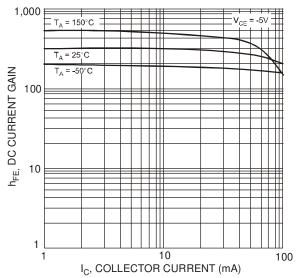


Fig. 2 Typical DC Current Gain vs. Collector Current

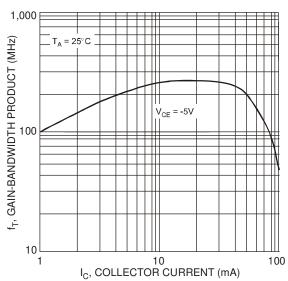


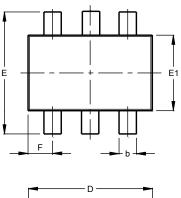
Fig. 4 Typical Gain-Bandwidth Product vs. Collector Current

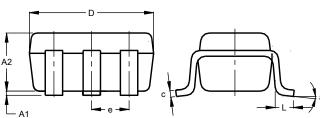


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



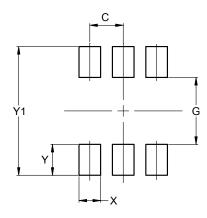


	SOT363						
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	1.00				
b	0.10	0.30	0.25				
С	0.10	0.22	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	0.650 BSC						
F	0.40	0.45	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
AII	All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT363



Dimensions	Value (in mm)		
С	0.650		
G	1.300		
X	0.420		
Υ	0.600		
V1	2 500		



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